National Semiconductor
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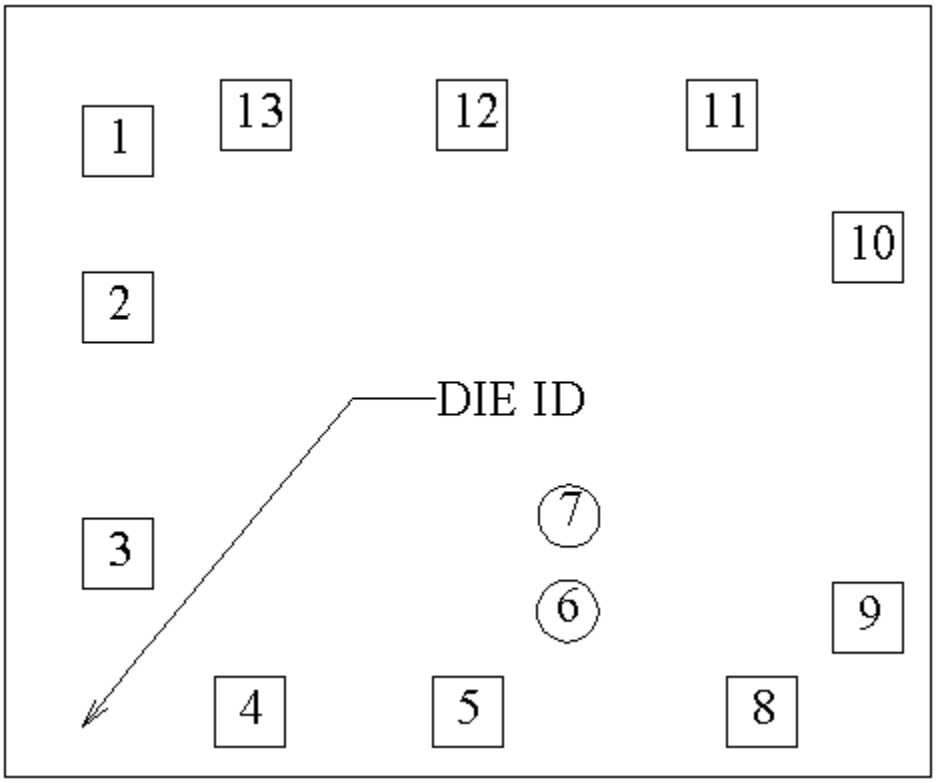
DPBU
Die Datasheet

LM723 MD8 MW8
VOLTAGE REGULATOR

July 22,2004

DIE LAYOUT (D-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	723D	Bond Pad Opening Size (min)	102μm x 102μm
Die Step	D	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1346μm x 1118μm 53.0mils x 44.0mils	Back Side Connection	Floating or V-
Thickness	406μm Nominal		
Min Pitch	204μm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (D -Step)

(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
CURRENT SENSE	1	-509	363	102	x	102
INPUT -	2	-509	121	102	x	102
INPUT +	3	-509	-237	102	x	102
VREF	4	-318	-466	102	x	102
V-	5	-1	-466	102	x	102
NC	6	145	-318	90	x	90
NC	7	147	-179	86	x	90
VZ	8	429	-466	102	x	102
VOUT	9	583	-329	102	x	102
VC	10	583	209	102	x	102
V+	11	369	401	102	x	102
FREQ COMP	12	7	401	102	x	102
CURRENT LIMIT	13	-309	401	102	x	102

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